

REMARKS/ARGUMENTS

Reconsideration of this application in light of the above amendments is courteously solicited.

Claims 1-10 were rejected under 35 U.S.C. 102(b) as being anticipated by Ning et al. (U.S. Patent No. 6,183,875).

The invention as claimed in the amended claim 1 is directed to a method for producing an aluminum/ceramic bonding substrate, said method comprising the steps of: causing an aluminum member having a plurality of 99.5% or more to contact at least one side of a ceramic substrate; and thereafter, heating the aluminum member and the ceramic substrate, which contacts the aluminum member, at a temperature of 620 to 650 °C in an inert gas to bond the aluminum member directly to the ceramic substrate.

The invention as claimed in the amended claim 6 is directed to an aluminum/ceramic bonding substrate comprising: a ceramic substrate; and an aluminum member having a purity of 99.5% or more, said aluminum member being bonded directly to at least one side of said ceramic substrate by heating the aluminum member and the ceramic substrate after causing the aluminum member to contact the ceramic substrate, wherein a peel strength between said aluminum member and said ceramic substrate is 49 N/cm or more.

Ning et al. teaches an electronic circuit substrate prepared by directly solidifying molten aluminum or aluminum alloy on a ceramic substrate. That is, the electronic circuit substrate of Ning et al. is produced by solidifying molten aluminum or the like after causing the molten aluminum or the like to contact the ceramic substrate. However, Ning et al. fails to suggest or disclose that a solid aluminum member, such as an aluminum plate, is bonded directly to a ceramic substrate by heating the aluminum member and the ceramic substrate after causing the aluminum member to contact the ceramic substrate.

Accordingly, it is believed that the amended claims patentably distinguish the invention from the prior art.

An earnest and thorough attempt has been made by the undersigned to resolve the outstanding issues in this case and place same in condition for allowance. If the Examiner has any questions or feels that a telephone or personal interview would be helpful in resolving any outstanding issues which remain in this application after consideration of this amendment, the Examiner is courteously invited to telephone the undersigned and the same would be gratefully appreciated.

It is submitted that the claims as amended herein patentably define over the art relied on by the Examiner and early allowance of same is courteously solicited.

If any fees are required in connection with this case, it
is respectfully requested that they be charged to Deposit
Account No. 02-0184.

Respectfully submitted,

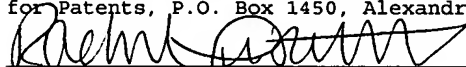
Takayuki Takahashi et al.

By 

Gregory P. LaPointe
Attorney for Applicants
Reg. No. 28,395
Tel: (203) 777-6628
Fax: (203) 865-0297

Date: August 30, 2004

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313" on August 30, 2004.


Rachel Piscitelli